

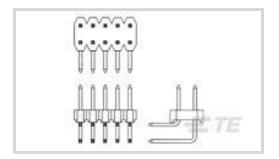
AMPMODU | AMPMODU 2 mm

TE Internal #: 3-1734507-0 PCB Mount Header, Right Angle, Board-to-Board, 30 Position, 2 mm [.079 in] Centerline, Breakaway, Gold, Through Hole - Solder, Signal, AMPMODU 2 mm

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Connectors > PCB Connectors > PCB Headers & Receptacles



PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Right Angle

Connector System: Board-to-Board

Number of Positions: **30**

Number of Rows: 2

Features

Product Type Features

PCB Connector Assembly Type

Connector System

Header Type

PCB Mount Header

Board-to-Board

Breakaway

| Sealable | No |
|---------------------------------------|-----------------------|
| Connector & Contact Terminates To | Printed Circuit Board |
| Configuration Features | |
| Connector Contact Load Condition | Fully Loaded |
| PCB Mount Orientation | Right Angle |
| Number of Positions | 30 |
| Number of Rows | 2 |
| Board-to-Board Configuration | Perpendicular |
| Electrical Characteristics | |
| Dielectric Withstanding Voltage (Max) | 500 VAC |
| Operating Voltage | 250 VAC |
| Body Features | |
| Primary Product Color | Black |
| Contact Features | |
| Contact Mating Area Length | 4 mm[.158 in] |

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| Mating Square Post Dimension | .5 mm[.02 in] |
|---|----------------------------|
| PCB Contact Termination Area Plating Material Thickness | 2.54 µm |
| Contact Shape & Form | Square |
| PCB Contact Termination Area Plating Material | Tin |
| Contact Base Material | Copper Alloy |
| Contact Mating Area Plating Material | Gold |
| Contact Mating Area Plating Material Thickness | .25 μm[10 μin] |
| Contact Type | Pin |
| Contact Current Rating (Max) | 1 A |
| Termination Features | |
| Square Termination Post & Tail Dimension | .5 mm[.02 in] |
| Termination Post & Tail Length | 2.6 mm[.102 in] |
| Termination Method to Printed Circuit Board | Through Hole - Solder |
| Mechanical Attachment | |
| Mating Alignment | Without |
| PCB Mount Retention | Without |
| PCB Mount Alignment | Without |
| Connector Mounting Type | Board Mount |
| Housing Features | |
| Centerline (Pitch) | 2 mm[.079 in] |
| Housing Material | Thermoplastic |
| Dimensions | |
| Row-to-Row Spacing | 2 mm[.079 in] |
| PCB Thickness (Recommended) | 1.6 mm[.063 in] |
| Usage Conditions | |
| Operating Temperature Range | -65 – 105 °C[-85 – 221 °F] |
| Operation/Application | |
| Circuit Application | Signal |
| Industry Standards | |
| UL Flammability Rating | UL 94V-0 |
| Packaging Features | |
| Packaging Type | Loose Piece |
| | |

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| Other | |
|--|---|
| Position Locations Omitted | 0 |
| Product Compliance For compliance documentation, visit the product page on TE.com> | |
| EU RoHS Directive 2011/65/EU | Compliant |
| EU ELV Directive 2000/53/EC | Compliant |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold |
| EU REACH Regulation (EC) No. 1907/2006 | Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JAN 207 (173) SVHC > Threshold: Not Yet Reviewed |
| Halogen Content | Not Yet Reviewed for halogen content |
| Solder Process Capability | Wave solder capable to 265°C |

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulations, TE's information on SVHC in articles for this part number is still based on the European Chemical Agency (ECHA) 'Guidance on requirements for substances in articles' (Version: 2, April 2011), applying the 0.1% weight on weight concentration threshold at the finished product level. TE is aware of the European Court of Justice ruling of September 10th, 2015 also known as O5A (Once An Article Always An Article) stating that, in case of 'complex object', the threshold for a SVHC must be applied to both the product as a whole and simultaneously to each of the articles forming part of its composition. TE has evaluated this ruling based on the new ECHA "Guidance on requirements for substances in articles" (June 2017, version 4.0) and will be updating its statements accordingly.

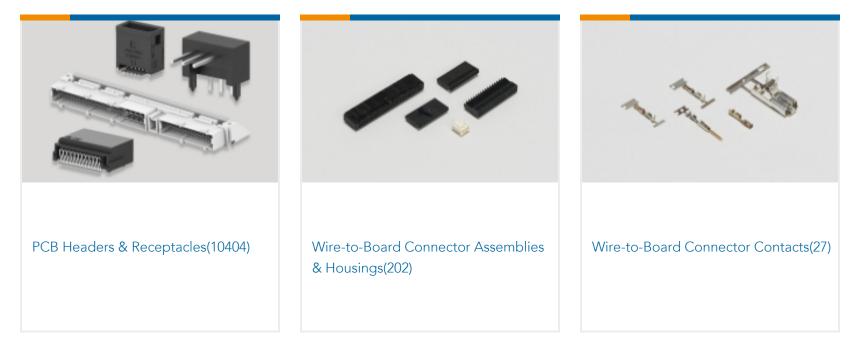
Compatible Parts



PCB Mount Header, Right Angle, Board-to-Board, 30 Position, 2 mm [.079 in] Centerline, Breakaway, Gold, Through Hole - Solder, Signal, AMPMODU 2 mm



Also in the Series AMPMODU 2 mm



Customers Also Bought





Documents

Product Drawings

HDR, 2mm pitch, 30P, R/A, MT, 8u" AU

English

CAD Files

Customer View Model ENG_CVM_CVM_3-1734507-0_B.2d_dxf.zip

English

3D PDF

3D

Customer View Model ENG_CVM_CVM_3-1734507-0_B.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_3-1734507-0_B.3d_stp.zip

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English

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Datasheets & Catalog Pages AMPMODU_INTERCONNECTION_SYSTEM_SECTION3AND4

English